

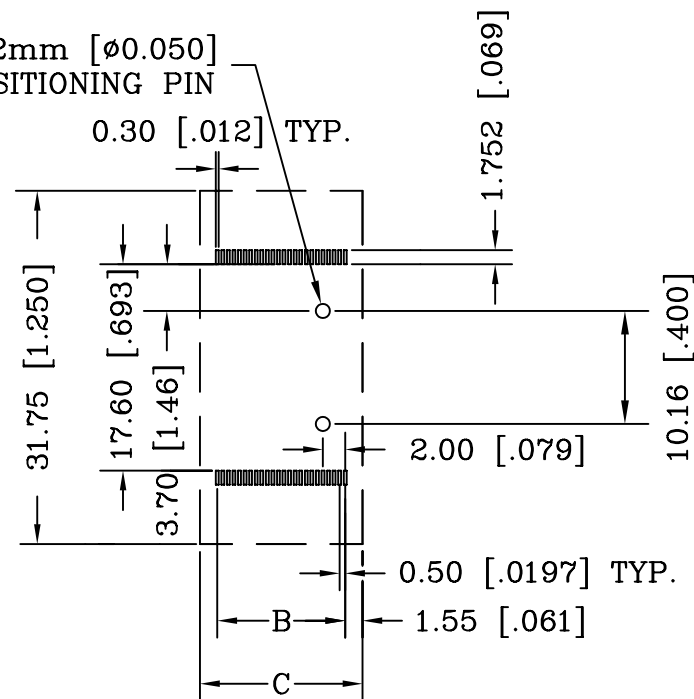
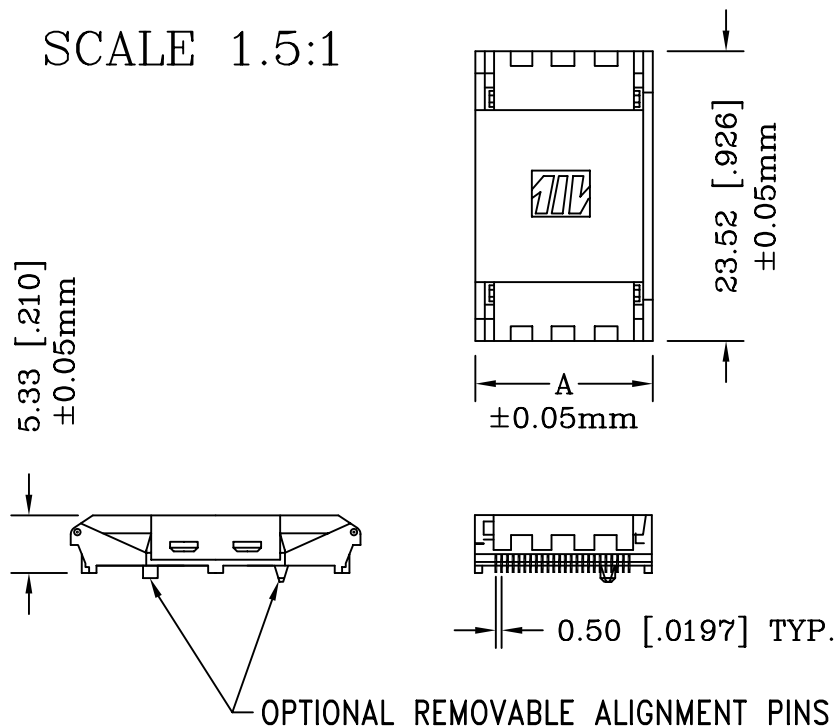
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	08/03/05	H.N.
B	UPDATED DIMENSIONS	06/27/06	H.N.
C	ADDED TOLERANCES	11/04/08	JAG

SKT2381

SOCKET LAND-PAD FOOTPRINT

SCALE 1.5:1

2X $\phi 1.27 \pm 0.12\text{mm}$ [$\phi 0.050$]
 OPTIONAL POSITIONING PIN



NO LEAD

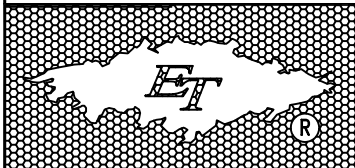
SPECIFICATIONS:

- FOR OEM, PROGRAMMING, PROTOTYPING AND TEST APPLICATIONS
- SURFACE MOUNT ZERO-INSERTION FORCE
- LAND-PAD FOOTPRINT COMMON FOR PACKAGE AND SOCKET
- BODY, LID AND LOCK MATERIAL: LCP
- TERMINAL MATERIAL: COPPER ALLOY, WITH PALLADIUM OVER NICKEL PLATING
- MINIMUM INSERTION/WITHDRAWAL CYCLES: 50
- TEMPERATURE RANGE: -55°C TO $+105^{\circ}\text{C}$
- CURRENT RATING: 0.5 AMP
- FLAMMABILITY: 940V-0
- PACKAGING: TRAY OR TAPE AND REEL.
- VERY POSITIVE LOCKING LID DESIGN

ET PACKAGE CODE	DIM A		DIM B		DIM C	
	mm	inches	mm	inches	mm	inches
56-TS01	15.85	.624	13.50	.531	17.63	.694

PACKAGE SPECIFICATIONS	
PIN COUNT	= 56
LEAD PITCH	= 0.50mm
PACKAGE WIDTH	= 18.40mm

ALL DIMENSIONS ARE IN MM [IN] UNLESS OTHERWISE SPECIFIED



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SHEET: 1 OF 1	DATE: 08/03/05	REVISION: C	ASSEMBLY DRAWING
CHECKED: Perry Munroe	DRAWN: Huy Nguyen		ITEM: S-TSO-SM-056-C1
Scale N/A	DO NOT SCALE DRAWING		DESCRIPTION: S-TSO-SM-056-C1